

REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE

A

B

C

D

E

F

A

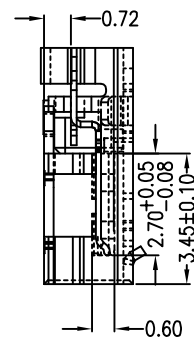
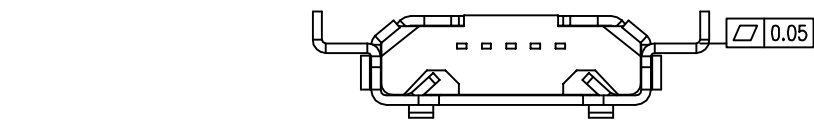
B

C

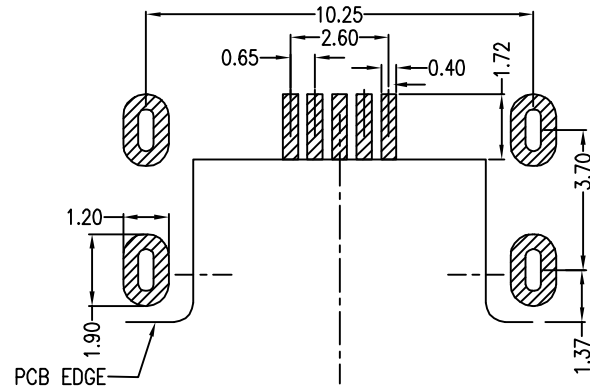
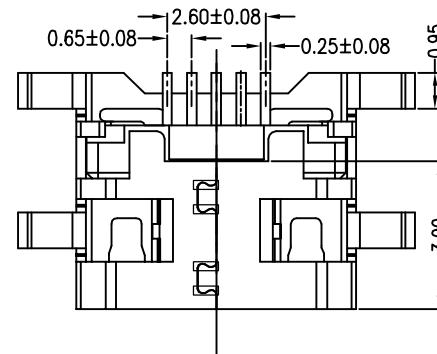
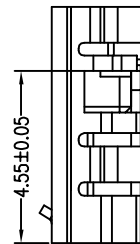
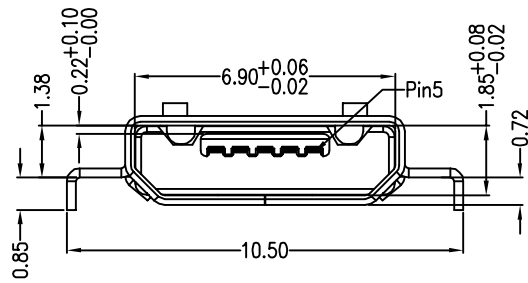
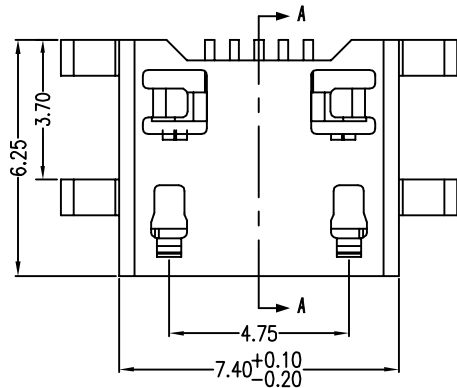
D

E

F



SEC A-A



RECOMMENDED PCB LAYOUT

Note:

1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.15mm
- 1.3 Shell: copper alloy,t=0.25mm

2.Specification:

- 2.1 Current rating: 1 A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 50 mW Max.
- 2.4 Insulation resistance: 100 MW Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.
- 2.7 Temperature range: -30°C~80°C

PART NO: HW-MUSBF-002-005		MATERIAL: SEE NOTE	东莞市鸿崑精密电子有限公司 Dongguan HongWei Electronic CO.,LTD	
MODEL NO: XX		FINSH: SEE NOTE		
UNIT: MM	SIZE: A4	COLOR: SEE NOTE	TITLE: Micro usb 5s B Type Smt沉板式无导位无接地片	
TOLERANCE UNSPECIFIED		DR: 夏友红	DWG NO: A259	
.x	0.25	CHK:	REV: A	
.xx	0.20	APP:	SCALE: 5:1	
.xxx	0.15		DATE: 2012.06.18	
Ang.	2'			

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